

BB02-KQ :- 2.54MM FEMALE HEADER, DUAL ROW, SIDE ENTRY, SMT TYPE, 4 TO 80 CONTACTS

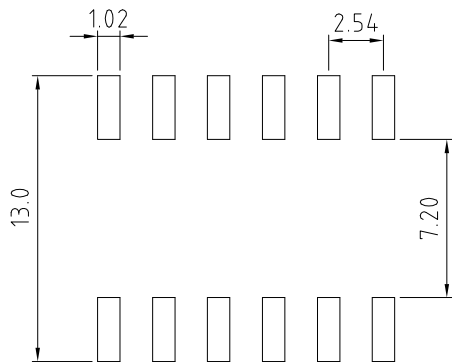
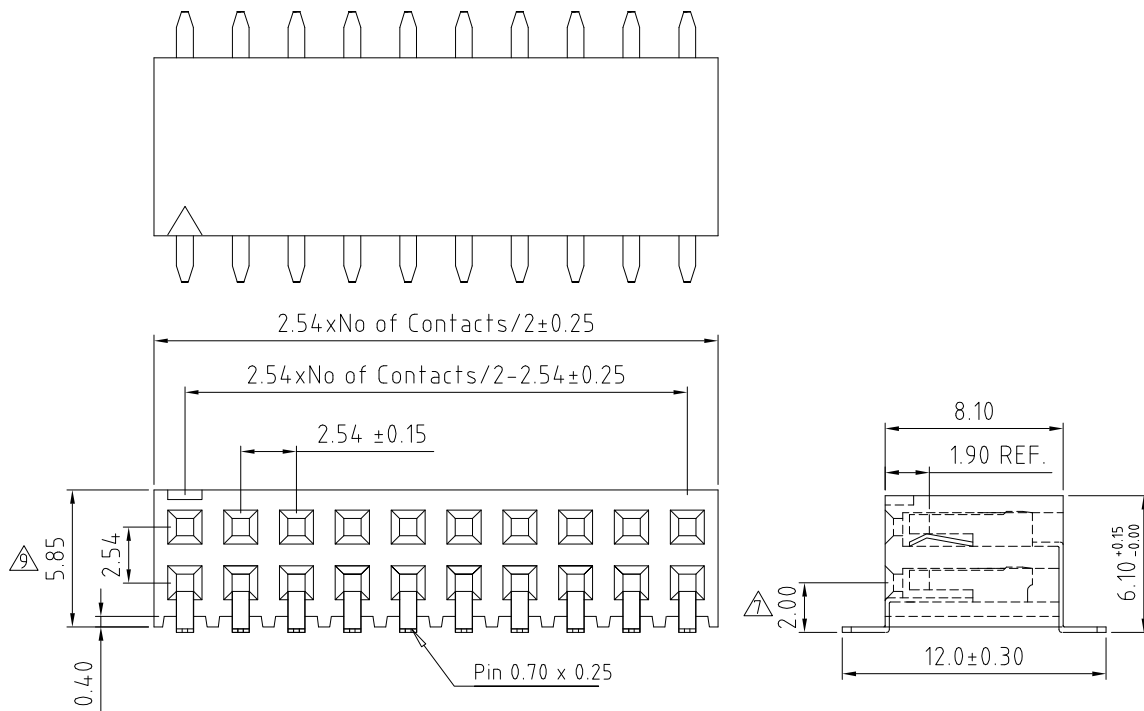
SPECIFICATIONS

CURRENT RATING	3 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	600 V AC/DC
CONTACT RESISTANCE	20m OHMS MAX.
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0 STANDARD NYLON 6T
PLATING	GOLD OR TIN OVER 30-50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC MANUAL SOLDER: 350°C FOR 3-5

NOTES:

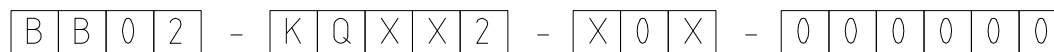
1. RECOMMENDED MATING PIN LENGTH: 4.5MM. \triangle
2. PARTS WITH SMALLER CONTACT NUMBERS MAY BE PACKED IN BOX INSTEAD OF IN TUBE.
3. MAX. NUMBER OF CONTACTS ALLOWED FOR TAPE & REEL PACKAGING: 64 CONTACTS.

MATES WITH: - BB02-HE BB02-HU
BB02-HJ BB02-TF
BB02-HP BB02-TG



RECOMMENDED PC BOARD LAYOUT

HOW TO ORDER



NO. OF CONTACTS:
04 TO 80

CONTACT PLATING OPTIONS: \triangle

- K = GOLD FLASH (STANDARD)
- A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- T = BRIGHT TIN
- M = MATT TIN

PACKAGING OPTIONS:
3 = TUBE (standard)
6 = TAPE & REEL
(see notes 2 & 3)

REV.	DATE/DRN	DESCRIPTION
10	11/11/04-CHC	RELEASE
11	14/08/06-CHC	DRAWING MODIFICATION
12	25/04/07-NYW	ADD DIMENSION
13	30/05/07-NYW	ADD NOTES 1
14	16/10/07-CHC	REMOVE SELECTIVE GOLD CONTACT PLATING
15	28/05/08-PN	ADD MATT TIN PLATING
16	13/02/09-NYW	DRAWING MODIFICATION
17	28/01/11-NYW	ADD PLANNER HEIGHT
18	24/10/13-NYW	ADD NOTES 2 & 3
19	09/12/15-NYW	AMEND CONNECTOR PROFILE

Scale: 4:1	THIRD ANGLE	Unstated Tolerances: X: ± 0.30 X: ± 0.25 XX: ± 0.15 XXX: ± 0.10	Material: SEE NOTE
Drawn: CHC			
App'd: NYW	Title: SOCKET		NOT TO SCALE
Date: 9 DEC. '15	Revision: 1.9		Unit: mm

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Type: BB02-KQ
BB02-KQ
Drawing Number:
Sheet 1 of 1
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